



FOR IMMEDIATE RELEASE

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Indium Corporation to Showcase High-Reliability Power Device Packaging Solutions at PCIM Asia 2026

CLINTON, N.Y., August 20, 2026 – As a leading provider of advanced materials solutions for power device packaging, [Indium Corporation](http://www.indium.com)® will feature its lineup of high-reliability products that are “Electrifying the Future” at [PCIM Asia 2026](#), August 26-28, in Shenzhen, China.

The company will feature the following products:

- [Formic Acid Soldering Technology \(FAST\)](#) is an ideal reflow method for power device packaging. Product offerings, including preforms, InFORMS®, and novel solder pastes, enable high-reliability, flux-free soldering, ideal for efficient manufacturing of next-generation power electronics.
- [InFORCE®](#) pressure sinter pastes are high-metal, low-organic content sinter materials available in both silver and copper. Its low-organic content composition affords short drying times for increased throughput and less volume reduction between wet and post-sintered deposits, reducing the paste amount required.
- [InFORCE®29](#) is a range of pressure Cu sinter pastes for applications where high reliability and high thermal conductivity are critical. Applications for InFORCE®29 include die-attach for Si and SiC power devices and substrate-attach of power modules directly to coolers.
- [InFORCE®MF](#) is a proven pressure Ag sinter paste designed for SiC die-attach application and is specially formulated for printing and dry-placement processes. This



paste offers outstanding die shear strength, thermal conductivity, and mechanical reliability.

- [InBAKE™29](#) is a Cu sinter paste developed for power discrete die-attach applications and applications requiring high thermal conductivity, high electrical conductivity, and high service/operating temperatures. It is specifically designed for pressureless, batch oven sintering.

To learn more about Indium Corporation's comprehensive portfolio of [power electronics packaging and assembly solutions](#), visit indium.com or meet our company experts at PCIM Asia, hall 16, booth F30.

About Indium Corporation

Indium Corporation® is a premier materials refiner, smelter, manufacturer, and supplier to the global electronics, semiconductor, thin-film, and thermal management markets. Products include solders and fluxes; brazes; thermal interface materials; sputtering targets; indium, gallium, germanium, and tin metals and inorganic compounds; and NanoFoil®. Founded in 1934, the company has global technical support and factories located in China, Germany, India, Malaysia, Mexico, Singapore, South Korea, the United Kingdom, and the U.S.

For more information about Indium Corporation, visit <http://www.indium.com/> or email jhuang@indium.com. You can also follow our experts, From One Engineer To Another® (#FOETA), at www.linkedin.com/company/indium-corporation/.

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